



Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	55
Program Memory Size	60KB (60K x 8)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s08rn60w1mlhr

- Input/Output
 - Up to 55 GPIOs including one output-only pin
 - Two 8-bit keyboard interrupt modules (KBI)
 - Two true open-drain output pins
 - Eight, ultra-high current sink pins supporting 20 mA source/sink current
- Package options
 - 64-pin LQFP
 - 48-pin LQFP
 - 32-pin LQFP

Table of Contents

1 Ordering parts.....	4	5.2.2 Debug trace timing specifications.....	17
1.1 Determining valid orderable parts.....	4	5.2.3 FTM module timing.....	17
2 Part identification.....	4	5.3 Thermal specifications.....	18
2.1 Description.....	4	5.3.1 Thermal characteristics.....	18
2.2 Format.....	4	6 Peripheral operating requirements and behaviors.....	19
2.3 Fields.....	4	6.1 External oscillator (XOSC) and ICS characteristics.....	20
2.4 Example.....	5	6.2 NVM specifications.....	21
3 Parameter Classification.....	5	6.3 Analog.....	23
4 Ratings.....	5	6.3.1 ADC characteristics.....	23
4.1 Thermal handling ratings.....	5	6.3.2 Analog comparator (ACMP) electricals.....	25
4.2 Moisture handling ratings.....	6	6.4 Communication interfaces.....	26
4.3 ESD handling ratings.....	6	6.4.1 SPI switching specifications.....	26
4.4 Voltage and current operating ratings.....	6	6.5 Human-machine interfaces (HMI).....	29
5 General.....	7	6.5.1 TSI electrical specifications.....	29
5.1 Nonswitching electrical specifications.....	7	7 Dimensions.....	29
5.1.1 DC characteristics.....	7	7.1 Obtaining package dimensions.....	29
5.1.2 Supply current characteristics.....	14	8 Pinout.....	30
5.1.3 EMC performance.....	15	8.1 Signal multiplexing and pin assignments.....	30
5.2 Switching specifications.....	16	8.2 Device pin assignment.....	33
5.2.1 Control timing.....	16	9 Revision history.....	35

1 Ordering parts

1.1 Determining valid orderable parts

Valid orderable part numbers are provided on the web. To determine the orderable part numbers for this device, go to www.freescale.com and perform a part number search for the following device numbers: RN60, RN48 and RN32.

2 Part identification

2.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

2.2 Format

Part numbers for this device have the following format:

S 9 S08 RN AA F1 B CC

2.3 Fields

This table lists the possible values for each field in the part number (not all combinations are valid):

Field	Description	Values
S	Qualification status	• S = fully qualified, general market flow
9	Memory	• 9 = flash based
S08	Core	• S08 = 8-bit CPU
RN	Device family	• RN
AA	Approximate flash size in KB	• 60 = 60 KB • 48 = 48 KB • 32 = 32 KB
F1	Fab and mask set identifier	• W1
B	Temperature range (°C)	• M = -40 to 125

Table continues on the next page...

Symbol	Description	Min.	Max.	Unit
V_{DIO}	Digital input voltage (except RESET, EXTAL, XTAL, or true open drain pin PTA2 and PTA3)	-0.3	$V_{DD} + 0.3$	V
	Digital input voltage (true open drain pin PTA2 and PTA3)	-0.3	6	V
V_{AIO}	Analog ¹ , RESET, EXTAL, and XTAL input voltage	-0.3	$V_{DD} + 0.3$	V
I_D	Instantaneous maximum current single pin limit (applies to all port pins)	-25	25	mA
V_{DDA}	Analog supply voltage	$V_{DD} - 0.3$	$V_{DD} + 0.3$	V

1. All digital I/O pins, except open-drain pin PTA2 and PTA3, are internally clamped to V_{SS} and V_{DD} . PTA2 and PTA3 is only clamped to V_{SS} .

5 General

5.1 Nonswitching electrical specifications

5.1.1 DC characteristics

This section includes information about power supply requirements and I/O pin characteristics.

Table 2. DC characteristics

Symbol	C	Descriptions			Min	Typical ¹	Max	Unit
—	—	Operating voltage			2.7	—	5.5	V
V_{OH}	C	Output high voltage	All I/O pins, standard-drive strength	5 V, $I_{load} = -5$ mA	$V_{DD} - 0.8$	—	—	V
	C			3 V, $I_{load} = -2.5$ mA	$V_{DD} - 0.8$	—	—	V
	C	High current drive pins, high-drive strength ^{2, 2}		5 V, $I_{load} = -20$ mA	$V_{DD} - 0.8$	—	—	V
	C			3 V, $I_{load} = -10$ mA	$V_{DD} - 0.8$	—	—	V
I_{OHT}	D	Output high current	Max total I_{OH} for all ports	5 V	—	—	-100	mA
				3 V	—	—	-50	
V_{OL}	C	Output low voltage	All I/O pins, standard-drive strength	5 V, $I_{load} = 5$ mA	—	—	0.8	V
	C			3 V, $I_{load} = 2.5$ mA	—	—	0.8	V
	C	High current drive pins, high-drive strength ²		5 V, $I_{load} = 20$ mA	—	—	0.8	V
	C			3 V, $I_{load} = 10$ mA	—	—	0.8	V

Table continues on the next page...

Table 2. DC characteristics (continued)

Symbol	C	Descriptions			Min	Typical ¹	Max	Unit
I_{OLT}	D	Output low current	Max total I_{OL} for all ports	5 V	—	—	100	mA
				3 V	—	—	50	
V_{IH}	P	Input high voltage	All digital inputs	$V_{DD} > 4.5V$	$0.70 \times V_{DD}$	—	—	V
	C			$V_{DD} > 2.7V$	$0.75 \times V_{DD}$	—	—	
V_{IL}	P	Input low voltage	All digital inputs	$V_{DD} > 4.5V$	—	—	$0.30 \times V_{DD}$	V
	C			$V_{DD} > 2.7V$	—	—	$0.35 \times V_{DD}$	
V_{hys}	C	Input hysteresis	All digital inputs	—	$0.06 \times V_{DD}$	—	—	mV
I_{In}	P	Input leakage current	All input only pins (per pin)	$V_{IN} = V_{DD}$ or V_{SS}	—	0.1	1	μA
I_{OZ}	P	Hi-Z (off-state) leakage current	All input/output (per pin)	$V_{IN} = V_{DD}$ or V_{SS}	—	0.1	1	μA
I_{OZTOT}	C	Total leakage combined for all inputs and Hi-Z pins	All input only and I/O	$V_{IN} = V_{DD}$ or V_{SS}	—	—	2	μA
R_{PU}	P	Pullup resistors	All digital inputs, when enabled (all I/O pins other than PTA2 and PTA3)	—	30.0	—	50.0	k Ω
R_{PU}^3	P	Pullup resistors	PTA2 and PTA3 pin	—	30.0	—	60.0	k Ω
I_{IC}	D	DC injection current ^{4, 5, 6}	Single pin limit	$V_{IN} < V_{SS}$, $V_{IN} > V_{DD}$	-0.2	—	2	mA
			Total MCU limit, includes sum of all stressed pins		-5	—	25	
C_{in}	C	Input capacitance, all pins		—	—	—	7	pF
V_{RAM}	C	RAM retention voltage		—	2.0	—	—	V

1. Typical values are measured at 25 °C. Characterized, not tested.
2. Only PTB4, PTB5 support ultra high current output.
3. The specified resistor value is the actual value internal to the device. The pullup value may appear higher when measured externally on the pin.
4. All functional non-supply pins, except for PTA2 and PTA3, are internally clamped to V_{SS} and V_{DD} .
5. Input must be current-limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive and negative clamp voltages, then use the large one.
6. Power supply must maintain regulation within operating V_{DD} range during instantaneous and operating maximum current conditions. If the positive injection current ($V_{IN} > V_{DD}$) is higher than I_{DD} , the injection current may flow out of V_{DD} and could result in external power supply going out of regulation. Ensure that external V_{DD} load will shunt current higher than maximum injection current when the MCU is not consuming power, such as no system clock is present, or clock rate is very low (which would reduce overall power consumption).

Table 3. LVD and POR Specification

Symbol	C	Description	Min	Typ	Max	Unit
V_{POR}	D	POR re-arm voltage ^{1, 2}	1.5	1.75	2.0	V

Table continues on the next page...

Typical I_{OH} Vs. $V_{DD}-V_{OH}$ (low drive strength) ($V_{DD} = 5\text{ V}$)

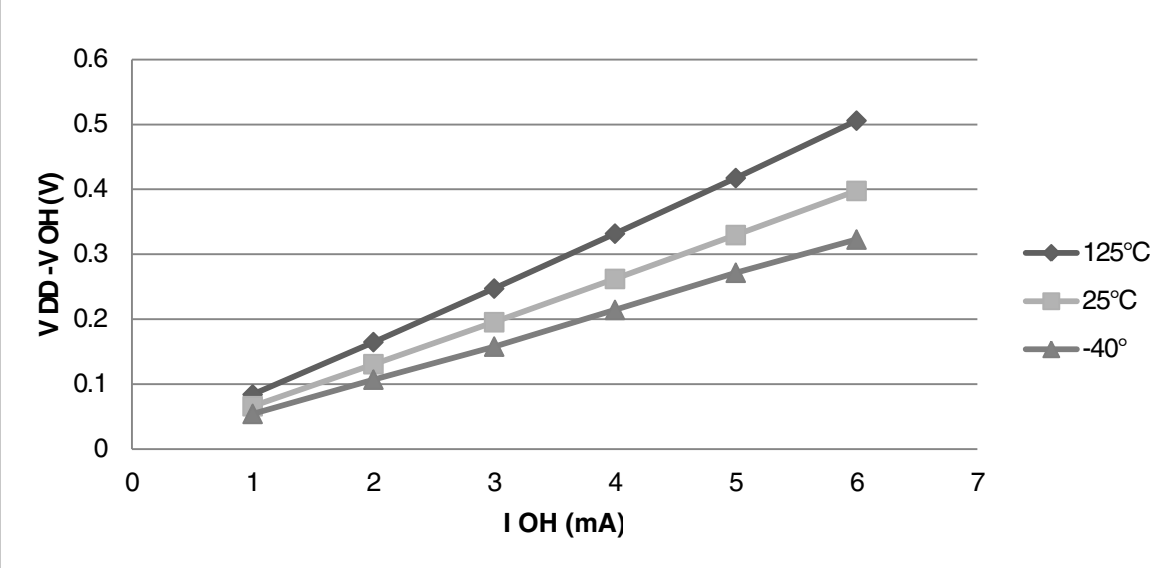


Figure 1. Typical I_{OH} Vs. $V_{DD}-V_{OH}$ (standard drive strength) ($V_{DD} = 5\text{ V}$)

Typical I_{OH} Vs. $V_{DD}-V_{OH}$ (low drive strength) ($V_{DD} = 3\text{ V}$)

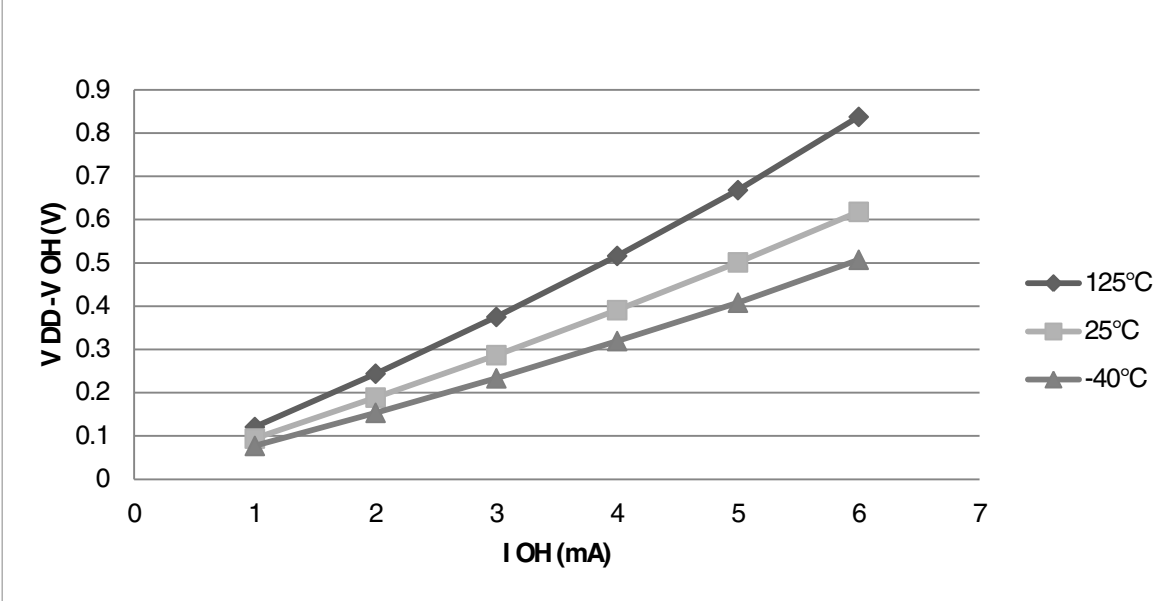


Figure 2. Typical I_{OH} Vs. $V_{DD}-V_{OH}$ (standard drive strength) ($V_{DD} = 3\text{ V}$)

Typical I_{OH} Vs. $V_{DD}-V_{OH}$ (high drive strength) ($V_{DD} = 5\text{ V}$)

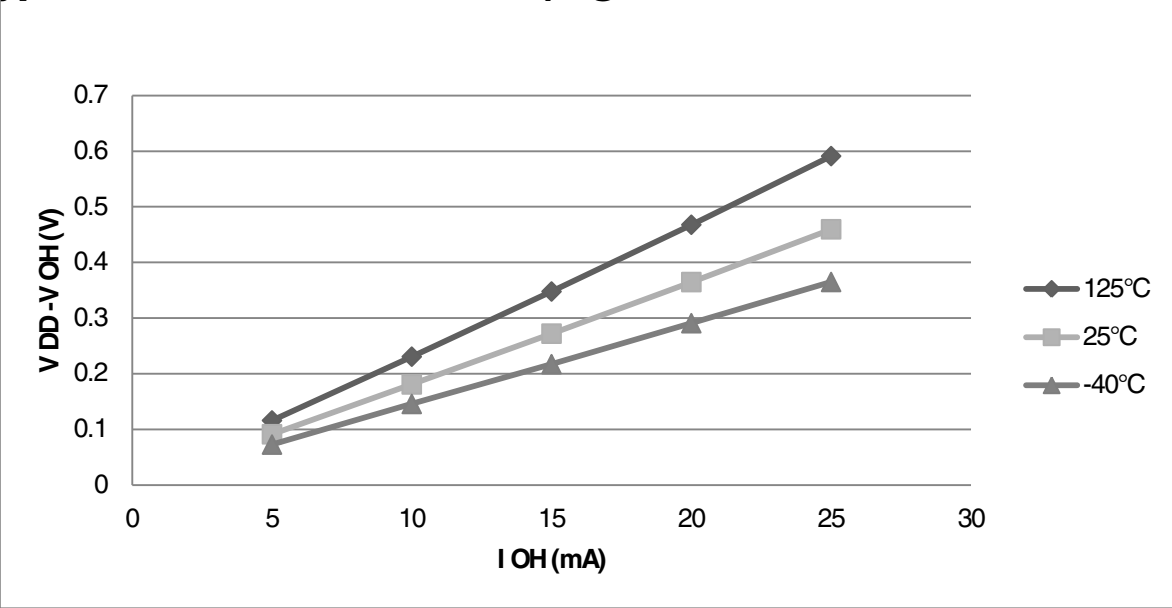


Figure 3. Typical I_{OH} Vs. $V_{DD}-V_{OH}$ (high drive strength) ($V_{DD} = 5\text{ V}$)

Typical I_{OH} Vs. $V_{DD}-V_{OH}$ (high drive strength) ($V_{DD} = 3\text{ V}$)

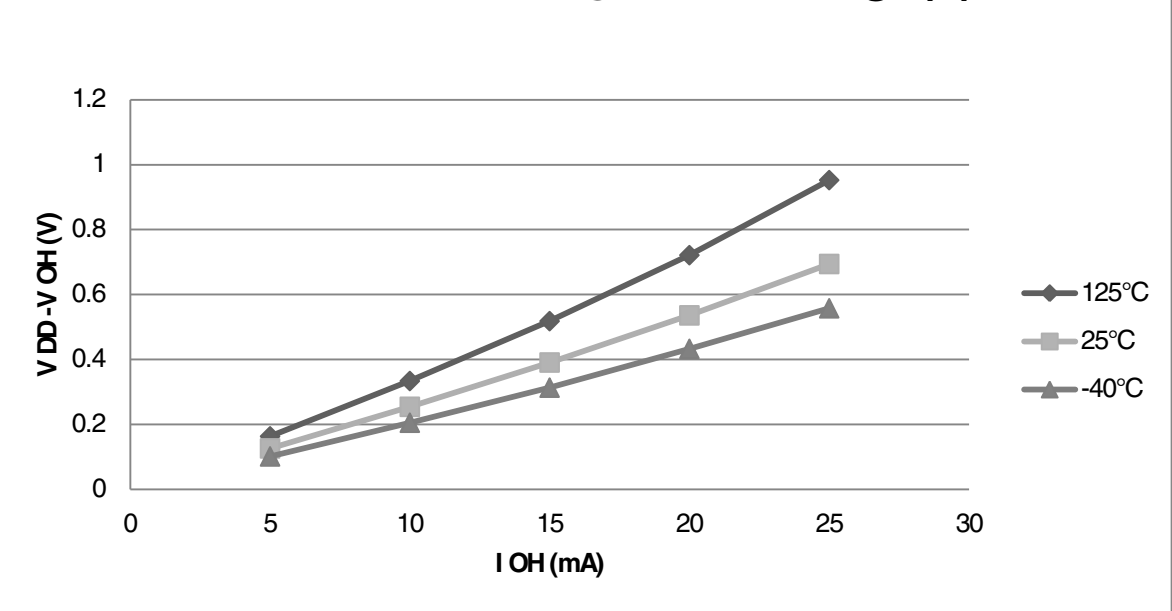


Figure 4. Typical I_{OH} Vs. $V_{DD}-V_{OH}$ (high drive strength) ($V_{DD} = 3\text{ V}$)

5.1.2 Supply current characteristics

This section includes information about power supply current in various operating modes.

Table 4. Supply current characteristics

Num	C	Parameter	Symbol	Bus Freq	V _{DD} (V)	Typical ¹	Max	Unit	Temp
1	C	Run supply current FEI mode, all modules on; run from flash	RI _{DD}	20 MHz	5	12.6	—	mA	-40 to 125 °C
	C			10 MHz		7.2	—		
	C			1 MHz		2.4	—		
	C			20 MHz	3	9.6	—		
	C			10 MHz		6.1	—		
	C			1 MHz		2.1	—		
2	C	Run supply current FEI mode, all modules off & gated; run from flash	RI _{DD}	20 MHz	5	10.5	—	mA	-40 to 125 °C
	C			10 MHz		6.2	—		
	C			1 MHz		2.3	—		
	C			20 MHz	3	7.4	—		
	C			10 MHz		5.0	—		
	C			1 MHz		2.0	—		
3	P	Run supply current FBE mode, all modules on; run from RAM	RI _{DD}	20 MHz	5	12.1	14.8	mA	-40 to 125 °C
	C			10 MHz		6.5	—		
	C			1 MHz		1.8	—		
	P			20 MHz	3	9.1	11.8		
	C			10 MHz		5.5	—		
	C			1 MHz		1.5	—		
4	P	Run supply current FBE mode, all modules off & gated; run from RAM	RI _{DD}	20 MHz	5	9.8	12.3	mA	-40 to 125 °C
	C			10 MHz		5.4	—		
	C			1 MHz		1.6	—		
	P			20 MHz	3	6.9	9.2		
	C			10 MHz		4.4	—		
	C			1 MHz		1.4	—		
5	C	Wait mode current FEI mode, all modules on	WI _{DD}	20 MHz	5	7.8	—	mA	-40 to 125 °C
	C			10 MHz		4.5	—		
	C			1 MHz		1.3	—		
	C			20 MHz	3	5.1	—		
	C			10 MHz		3.5	—		
	C			1 MHz		1.2	—		
6	C	Stop3 mode supply current no clocks active (except 1 kHz LPO clock) ^{2,3}	S3I _{DD}	—	5	3.8	—	μA	-40 to 125 °C
	C			—	3	3	—		-40 to 125 °C

Table continues on the next page...

Table 4. Supply current characteristics (continued)

Num	C	Parameter	Symbol	Bus Freq	V _{DD} (V)	Typical ¹	Max	Unit	Temp
7	C	ADC adder to stop3	—	—	5	44	—	μA	-40 to 125 °C
	C	ADLPC = 1 ADLSMP = 1 ADCO = 1 MODE = 10B ADICLK = 11B			3	40	—		
8	C	TSI adder to stop3 ⁴	—	—	5	111	—	μA	-40 to 125 °C
	C	PS = 010B NSCN = 0x0F EXTCHRG = 0 REFCHRG = 0 DVOLT = 01B			3	110	—		
9	C	LVD adder to stop3 ⁵	—	—	5	130	—	μA	-40 to 125 °C
	C				3	125	—		

1. Data in Typical column was characterized at 5.0 V, 25 °C or is typical recommended value.
2. RTC adder cause <1 μA I_{DD} increase typically, RTC clock source is 1 kHz LPO clock.
3. ACMP adder cause <1 μA I_{DD} increase typically.
4. The current varies with TSI configuration and capacity of touch electrode. Please refer to [TSI electrical specifications](#).
5. LVD is periodically woken up from stop3 by 5% duty cycle. The period is equal to or less than 2 ms.

5.1.3 EMC performance

Electromagnetic compatibility (EMC) performance is highly dependant on the environment in which the MCU resides. Board design and layout, circuit topology choices, location and characteristics of external components as well as MCU software operation all play a significant role in EMC performance. The system designer should consult Freescale applications notes such as AN2321, AN1050, AN1263, AN2764, and AN1259 for advice and guidance specifically targeted at optimizing EMC performance.

5.1.3.1 EMC radiated emissions operating behaviors

5.2 Switching specifications

5.2.1 Control timing

Table 5. Control timing

Num	C	Rating		Symbol	Min	Typical ¹	Max	Unit
1	P	Bus frequency ($t_{cyc} = 1/f_{Bus}$)		f_{Bus}	DC	—	20	MHz
2	P	Internal low power oscillator frequency		f_{LPO}	0.67	1.0	1.25	KHz
3	D	External reset pulse width ^{2, 2}		t_{extrst}	$1.5 \times t_{Self_reset}$	—	—	ns
4	D	Reset low drive		t_{rstdrv}	$34 \times t_{cyc}$	—	—	ns
5	D	BKGD/MS setup time after issuing background debug force reset to enter user or BDM modes		t_{MSSU}	500	—	—	ns
6	D	BKGD/MS hold time after issuing background debug force reset to enter user or BDM modes ³		t_{MSH}	100	—	—	ns
7	D	Keyboard interrupt pulse width	Asynchronous path ²	t_{ILIH}	100	—	—	ns
	D		Synchronous path	t_{IHIL}	$1.5 \times t_{cyc}$	—	—	ns
8	C	Port rise and fall time - Normal drive strength (HDRV_PTXx = 0) (load = 50 pF) ^{4, 4}	—	t_{Rise}	—	10.2	—	ns
	C			t_{Fall}	—	9.5	—	ns
	C	Port rise and fall time - Extreme high drive strength (HDRV_PTXx = 1) (load = 50 pF) ⁴	—	t_{Rise}	—	5.4	—	ns
	C			t_{Fall}	—	4.6	—	ns

1. Typical values are based on characterization data at $V_{DD} = 5.0$ V, 25 °C unless otherwise stated.

2. This is the shortest pulse that is guaranteed to be recognized as a reset pin request.

3. To enter BDM mode following a POR, BKGD/MS must be held low during the powerup and for a hold time of t_{MSH} after V_{DD} rises above V_{LVD} .

4. Timing is shown with respect to 20% V_{DD} and 80% V_{DD} levels. Temperature range -40 °C to 125 °C.

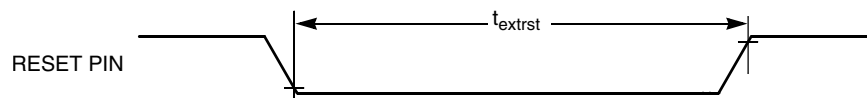


Figure 9. Reset timing

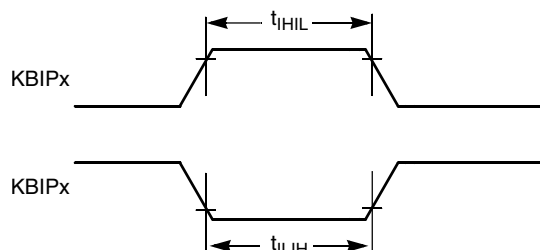


Figure 10. KBIPx timing

5.2.2 Debug trace timing specifications

Table 6. Debug trace operating behaviors

Symbol	Description	Min.	Max.	Unit
t_{cyc}	Clock period	Frequency dependent		MHz
t_{wl}	Low pulse width	2	—	ns
t_{wh}	High pulse width	2	—	ns
t_r	Clock and data rise time	—	3	ns
t_f	Clock and data fall time	—	3	ns
t_s	Data setup	3	—	ns
t_h	Data hold	2	—	ns

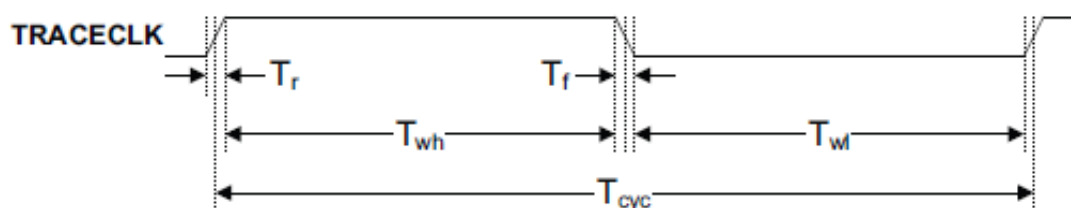


Figure 11. TRACE_CLKOUT specifications

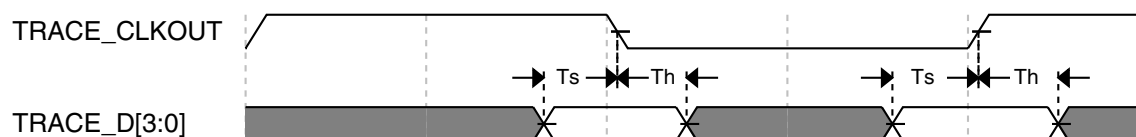


Figure 12. Trace data specifications

5.2.3 FTM module timing

Synchronizer circuits determine the shortest input pulses that can be recognized or the fastest clock that can be used as the optional external source to the timer counter. These synchronizers operate from the current bus rate clock.

Table 7. FTM input timing

No.	C	Function	Symbol	Min	Max	Unit
1	D	External clock frequency	f_{TCLK}	0	$f_{Bus}/4$	Hz

Table continues on the next page...

Table 7. FTM input timing (continued)

No.	C	Function	Symbol	Min	Max	Unit
2	D	External clock period	t_{TCLK}	4	—	t_{cyc}
3	D	External clock high time	t_{clkh}	1.5	—	t_{cyc}
4	D	External clock low time	t_{clkl}	1.5	—	t_{cyc}
5	D	Input capture pulse width	t_{ICPW}	1.5	—	t_{cyc}

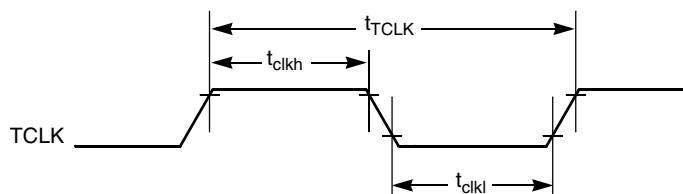


Figure 13. Timer external clock

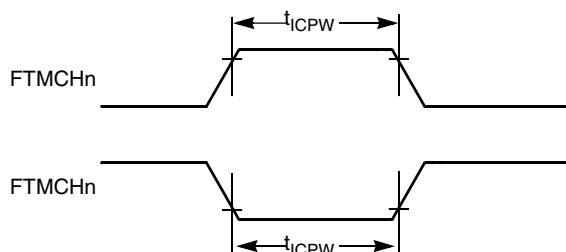


Figure 14. Timer input capture pulse

5.3 Thermal specifications

5.3.1 Thermal characteristics

This section provides information about operating temperature range, power dissipation, and package thermal resistance. Power dissipation on I/O pins is usually small compared to the power dissipation in on-chip logic and voltage regulator circuits, and it is user-determined rather than being controlled by the MCU design. To take $P_{I/O}$ into account in power calculations, determine the difference between actual pin voltage and V_{SS} or V_{DD} and multiply by the pin current for each I/O pin. Except in cases of unusually high pin current (heavy loads), the difference between pin voltage and V_{SS} or V_{DD} will be very small.

6.1 External oscillator (XOSC) and ICS characteristics

Table 9. XOSC and ICS specifications (temperature range = -40 to 125 °C ambient)

Num	C	Characteristic		Symbol	Min	Typical ¹	Max	Unit
1	C	Oscillator crystal or resonator	Low range (RANGE = 0)	f_{lo}	32	—	40	kHz
	C		High range (RANGE = 1) FEE or FBE mode ^{2, 2}	f_{hi}	4	—	20	MHz
	C		High range (RANGE = 1), high gain (HGO = 1), FBELP mode	f_{hi}	4	—	20	MHz
	C		High range (RANGE = 1), low power (HGO = 0), FBELP mode	f_{hi}	4	—	20	MHz
2	D	Load capacitors		C1, C2	See Note ³			
3	D	Feedback resistor	Low Frequency, Low-Power Mode ^{4, 4}	R_F	—	—	—	MΩ
			Low Frequency, High-Gain Mode		—	10	—	MΩ
			High Frequency, Low-Power Mode		—	1	—	MΩ
			High Frequency, High-Gain Mode		—	1	—	MΩ
4	D	Series resistor - Low Frequency	Low-Power Mode ⁴	R_S	—	—	—	kΩ
			High-Gain Mode		—	200	—	kΩ
5	D	Series resistor - High Frequency	Low-Power Mode ⁴	R_S	—	—	—	kΩ
	D	Series resistor - High Frequency, High-Gain Mode	4 MHz		—	0	—	kΩ
	D		8 MHz		—	0	—	kΩ
	D		16 MHz		—	0	—	kΩ
6	C	Crystal start-up time Low range = 39.0625 kHz crystal; High range = 20 MHz crystal ^{5, 5, 6}	Low range, low power	t_{CSTL}	—	1000	—	ms
	C		Low range, high power	t_{CSTL}	—	800	—	ms
	C		High range, low power	t_{CSTH}	—	3	—	ms
	C		High range, high power	t_{CSTH}	—	1.5	—	ms
7	T	Internal reference start-up time		t_{IRST}	—	20	50	μs
8	D	Square wave input clock frequency	FEE or FBE mode ²	f_{extal}	0.03125	—	5	MHz
	D		FBELP mode		0	—	20	MHz
9	P	Average internal reference frequency - trimmed		f_{int_t}	—	39.0625	—	kHz
10	P	DCO output frequency range - trimmed		f_{dco_t}	16	—	20	MHz

Table continues on the next page...

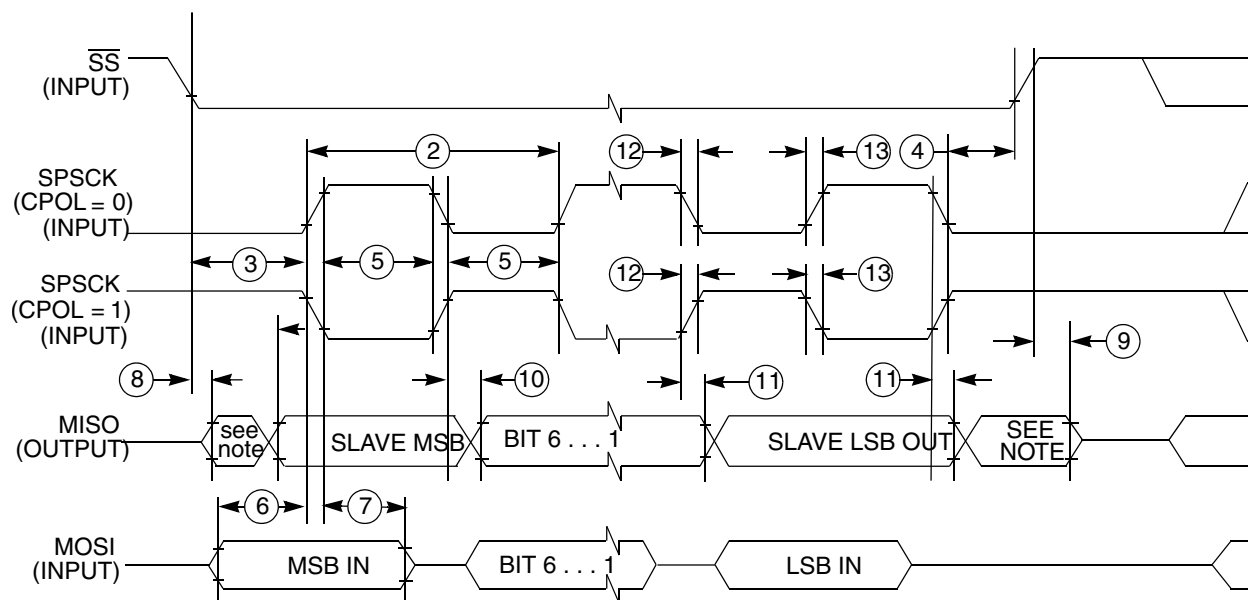
Table 12. 12-bit ADC Characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$) (continued)

Characteristic	Conditions	C	Symb	Min	Typ ¹	Max	Unit
ADC asynchronous clock source	High speed (ADLPC = 0)	P	f_{ADACK}	2	3.3	5	MHz
	Low power (ADLPC = 1)			1.25	2	3.3	
Conversion time (including sample time)	Short sample (ADLSMP = 0)	T	t_{ADC}	—	20	—	ADCK cycles
	Long sample (ADLSMP = 1)			—	40	—	
Sample time	Short sample (ADLSMP = 0)	T	t_{ADS}	—	3.5	—	ADCK cycles
	Long sample (ADLSMP = 1)			—	23.5	—	
Total unadjusted Error ^{2, 2}	12-bit mode	T	E_{TUE}	—	±5.0	—	LSB ^{3, 3}
	10-bit mode	P		—	±1.5	±2.0	
	8-bit mode	P		—	±0.7	±1.0	
Differential Non-Linearity	12-bit mode	T	DNL	—	±1.0	—	LSB ³
	10-bit mode ^{4, 4}	P		—	±0.25	±0.5	
	8-bit mode ⁴	P		—	±0.15	±0.25	
Integral Non-Linearity	12-bit mode	T	INL	—	±1.0	—	LSB ³
	10-bit mode	T		—	±0.3	±0.5	
	8-bit mode	T		—	±0.15	±0.25	
Zero-scale error ^{5, 5}	12-bit mode	C	E_{ZS}	—	±2.0	—	LSB ³
	10-bit mode	P		—	±0.25	±1.0	
	8-bit mode	P		—	±0.65	±1.0	
Full-scale error ⁶	12-bit mode	T	E_{FS}	—	±2.5	—	LSB ³
	10-bit mode	T		—	±0.5	±1.0	
	8-bit mode	T		—	±0.5	±1.0	
Quantization error	≤12 bit modes	D	E_Q	—	—	±0.5	LSB ³
Input leakage error ⁷	all modes	D	E_{IL}	$I_{in} * R_{AS}$			mV
Temp sensor slope	-40°C– 25°C	D	m	—	3.266	—	mV/°C
	25°C– 125°C			—	3.638	—	
Temp sensor voltage	25°C	D	V_{TEMP25}	—	1.396	—	V

1. Typical values assume $V_{DDA} = 5.0$ V, Temp = 25°C, $f_{ADCK}=1.0$ MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
2. Includes quantization.
3. $1 \text{ LSB} = (V_{REFH} - V_{REFL})/2^N$
4. Monotonicity and no-missing-codes guaranteed in 10-bit and 8-bit modes
5. $V_{ADIN} = V_{SSA}$
6. $V_{ADIN} = V_{DDA}$
7. I_{in} = leakage current (refer to DC characteristics)

Table 15. SPI slave mode timing

Nu m.	Symbol	Description	Min.	Max.	Unit	Comment
1	f_{op}	Frequency of operation	0	$f_{Bus}/4$	Hz	f_{Bus} is the bus clock as defined in .
2	t_{SPSCK}	SPSCK period	$4 \times t_{Bus}$	—	ns	$t_{Bus} = 1/f_{Bus}$
3	t_{Lead}	Enable lead time	1	—	t_{Bus}	—
4	t_{Lag}	Enable lag time	1	—	t_{Bus}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	$t_{Bus} - 30$	—	ns	—
6	t_{SU}	Data setup time (inputs)	15	—	ns	—
7	t_{HI}	Data hold time (inputs)	25	—	ns	—
8	t_a	Slave access time	—	t_{Bus}	ns	Time to data active from high-impedance state
9	t_{dis}	Slave MISO disable time	—	t_{Bus}	ns	Hold time to high-impedance state
10	t_v	Data valid (after SPSCK edge)	—	25	ns	—
11	t_{HO}	Data hold time (outputs)	0	—	ns	—
12	t_{RI}	Rise time input	—	$t_{Bus} - 25$	ns	—
	t_{FI}	Fall time input	—	$t_{Bus} - 25$	ns	—
13	t_{RO}	Rise time output	—	25	ns	—
	t_{FO}	Fall time output	—	25	ns	—



NOTE: Not defined

Figure 19. SPI slave mode timing (CPHA = 0)

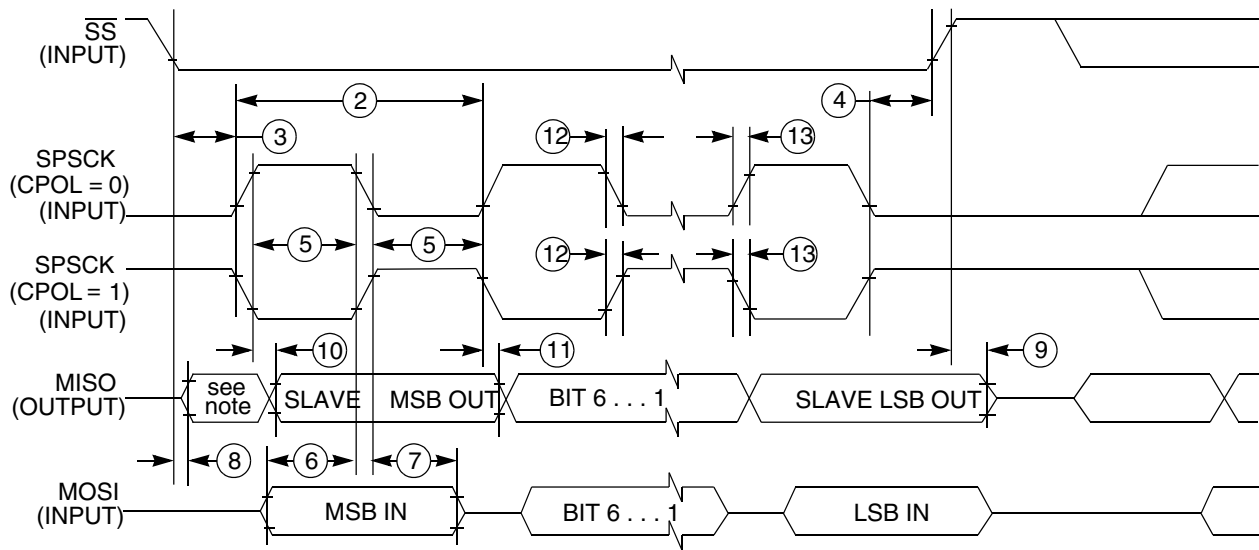


Figure 20. SPI slave mode timing (CPHA=1)

6.5 Human-machine interfaces (HMI)

6.5.1 TSI electrical specifications

Table 16. TSI electrical specifications

Symbol	Description	Min.	Type	Max	Unit
TSI_RUNF	Fixed power consumption in run mode	—	100	—	μA
TSI_RUNV	Variable power consumption in run mode (depends on oscillator's current selection)	1.0	—	128	μA
TSI_EN	Power consumption in enable mode	—	100	—	μA
TSI_DIS	Power consumption in disable mode	—	1.2	—	μA
TSI_TEN	TSI analog enable time	—	66	—	μs
TSI_CREF	TSI reference capacitor	—	1.0	—	pF
TSI_DVOLT	Voltage variation of VP & VM around nominal values	-10	—	10	%

7 Dimensions

7.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to freescale.com and perform a keyword search for the drawing's document number:

If you want the drawing for this package	Then use this document number
32-pin LQFP	98ASH70029A
48-pin LQFP	98ASH00962A
64-pin LQFP	98ASS23234W

8 Pinout

8.1 Signal multiplexing and pin assignments

The following table shows the signals available on each pin and the locations of these pins on the devices supported by this document. The Port Control Module is responsible for selecting which ALT functionality is available on each pin.

Table 17. Pin availability by package pin-count

Pin Number			Lowest Priority <-- --> Highest				
64-LQFP	48-LQFP	32-LQFP	Port Pin	Alt 1	Alt 2	Alt 3	Alt 4
1	1	1	PTD1 ^{1, 1}	KBI1P1	FTM2CH3	MOSI1	—
2	2	2	PTD0 ¹	KBI1P0	FTM2CH2	SPSCK1	—
3	—	—	PTH7	—	—	—	—
4	—	—	PTH6	—	—	—	—
5	3	—	PTE7	—	TCLK2	—	—
6	4	—	PTH2	—	BUSOUT	—	—
7	5	3	—	—	—	—	V _{DD}
8	6	4	—	—	—	V _{DDA}	V _{REFH}
9	7	5	—	—	—	V _{SSA}	V _{REFL}
10	8	6	—	—	—	—	V _{SS}
11	9	7	PTB7	—	SCL	—	EXTAL
12	10	8	PTB6	—	SDA	—	XTAL
13	11	—	—	—	—	—	V _{SS}
14	—	—	PTH1 ¹	—	FTM2CH1	—	—
15	—	—	PTH0 ¹	—	FTM2CH0	—	—
16	12	—	PTE6	—	—	—	—
17	13	—	PTE5	—	—	—	—
18	14	9	PTB5 ¹	FTM2CH5	SS0	—	—
19	15	10	PTB4 ¹	FTM2CH4	MISO0	—	—

Table continues on the next page...

Table 17. Pin availability by package pin-count (continued)

Pin Number			Lowest Priority <-- --> Highest				
64-LQFP	48-LQFP	32-LQFP	Port Pin	Alt 1	Alt 2	Alt 3	Alt 4
20	16	11	PTC3	FTM2CH3	—	ADP11	—
21	17	12	PTC2	FTM2CH2	—	ADP10	—
22	18	—	PTD7	KBI1P7	TXD2	—	—
23	19	—	PTD6	KBI1P6	RXD2	—	—
24	20	—	PTD5	KBI1P5	—	—	—
25	21	13	PTC1	—	FTM2CH1	ADP9	TSI7
26	22	14	PTC0	—	FTM2CH0	ADP8	TSI6
27	—	—	PTF7	—	—	ADP15	—
28	—	—	PTF6	—	—	ADP14	—
29	—	—	PTF5	—	—	ADP13	—
30	—	—	PTF4	—	—	ADP12	—
31	23	15	PTB3	KBI0P7	MOSI0	ADP7	TSI5
32	24	16	PTB2	KBI0P6	SPSCK0	ADP6	TSI4
33	25	17	PTB1	KBI0P5	TXD0	ADP5	TSI3
34	26	18	PTB0	KBI0P4	RXD0	ADP4	TSI2
35	—	—	PTF3	—	—	—	TSI15
36	—	—	PTF2	—	—	—	TSI14
37	27	19	PTA7	FTM2FAULT2	—	ADP3	TSI1
38	28	20	PTA6	FTM2FAULT1	—	ADP2	TSI0
39	29	—	PTE4	—	—	—	—
40	30	—	—	—	—	—	V _{SS}
41	31	—	—	—	—	—	V _{DD}
42	—	—	PTF1	—	—	—	TSI13
43	—	—	PTF0	—	—	—	TSI12
44	32	—	PTD4	KBI1P4	—	—	—
45	33	21	PTD3	KBI1P3	SS1	—	TSI11
46	34	22	PTD2	KBI1P2	MISO1	—	TSI10
47	35	23	PTA3 ^{2, 2}	KBI0P3	TXD0	SCL	—
48	36	24	PTA2 ²	KBI0P2	RXD0	SDA	—
49	37	25	PTA1	KBI0P1	FTM0CH1	ACMP1	ADP1
50	38	26	PTA0	KBI0P0	FTM0CH0	ACMP0	ADP0
51	39	27	PTC7	—	TxD1	—	TSI9
52	40	28	PTC6	—	RxD1	—	TSI8
53	41	—	PTE3	—	SS0	—	—
54	42	—	PTE2	—	MISO0	—	—
55	—	—	PTG3	—	—	—	—
56	—	—	PTG2	—	—	—	—
57	—	—	PTG1	—	—	—	—

Table continues on the next page...

8.2 Device pin assignment

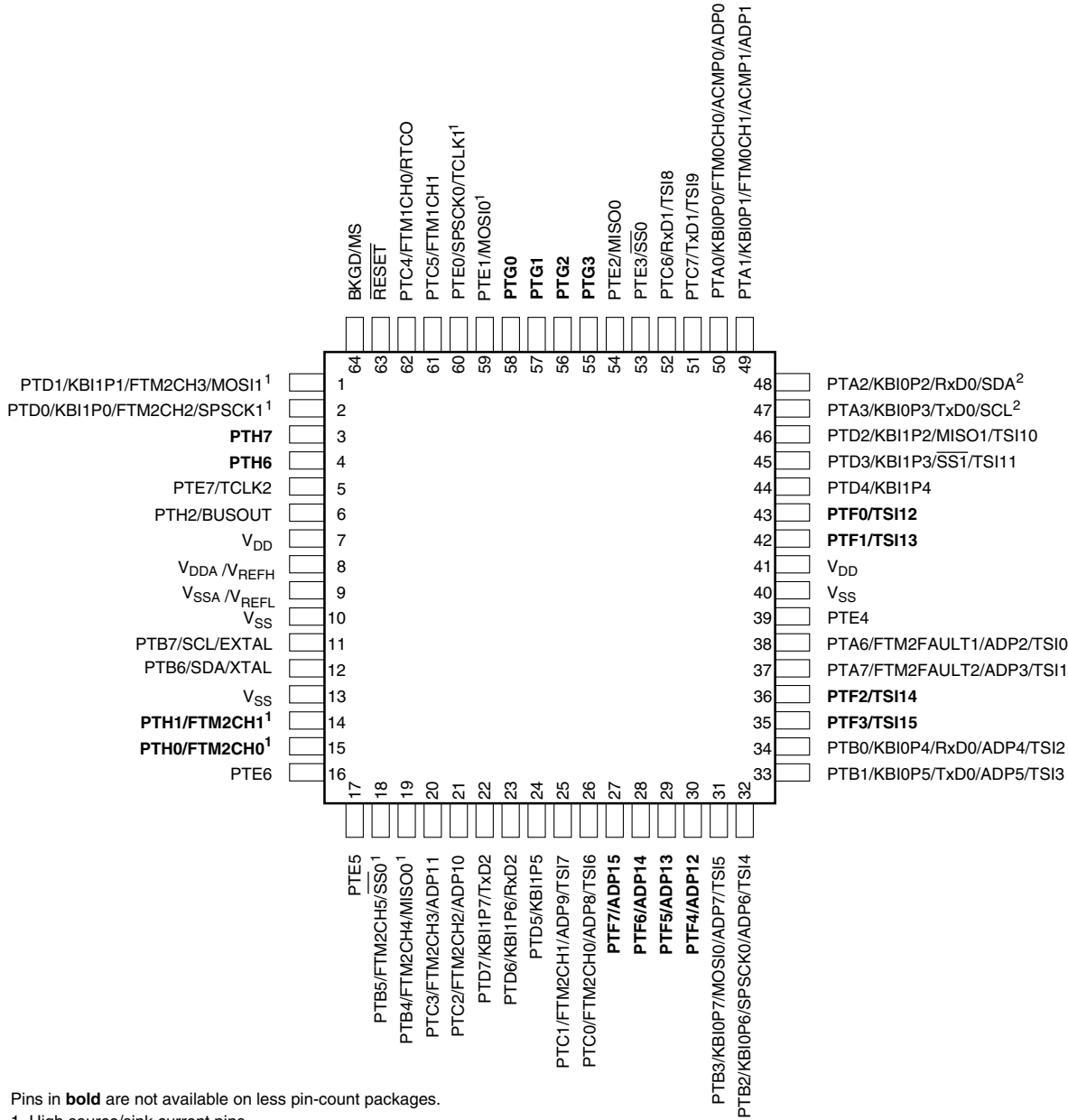
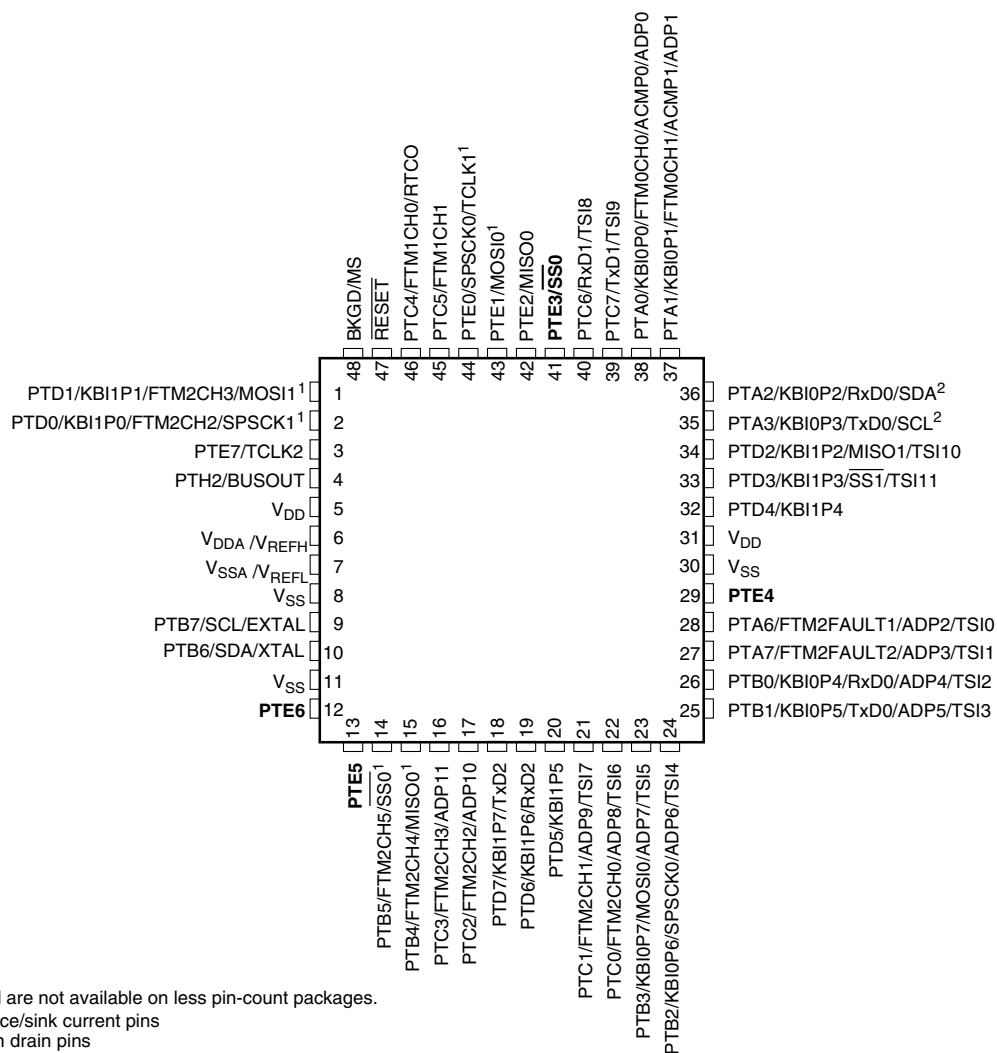


Figure 21. S9S08RN60 64-pin LQFP package



Pins in **bold** are not available on less pin-count packages.

1. High source/sink current pins

2. True open drain pins

Figure 22. S9S08RN60 48-pin LQFP package